

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Amador, et al.

Docket No.: TI-30592.1

Serial No.: TBD

Examiner: TBD

Filed: Herewith

Art Unit: TBD

For: Fixture and Method for Uniform Electroless Metal Deposition on Integrated  
Circuit Bond Pads

**Preliminary Amendment**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with  
the U.S. Postal Service as First Class Mail in an envelope addressed  
to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-  
1450 on

*December 8, 2003*  
*Elizabeth Austin*  
Elizabeth Austin

Please enter the following amendments prior to examination of the instant application. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of this paper to Texas Instruments Incorporated deposit account no. 20-0668.